

**Amendments to the Specification:**

Please add the following paragraphs after page 6, line 12:

FIG. 4 is a flowchart of an embodiment of the present invention.

FIG. 5 depicts an embodiment of the invention wherein an etchant dispenser or cathode assembly moves relative to one another over a cathode assembly.

FIG. 6 depicts an embodiment of the invention wherein an etchant dispenser or cathode assembly moves relative to one another over a cathode assembly in elongated spray zones.

Please amend the second full paragraph on page 8 as follows:

To perform the localized etching of the bond pads, wet etchant is preferably applied on the bond pads in elongated spray zones 112 in the peripheral area 104 of the panel 100. To form the elongated spray zones 112, the etchant is preferably sprayed from a nozzle 114 as it is moved linearly over the panel. Alternatively, the nozzle 114 can be held stationary and the panel moved relative to the nozzle 114 to create the spray zone ~~(FIG. 5)~~ (FIGs. 5 and 6).